

JEAN-151-SN100C-T4

Rev: 20.10

Date	2021.08.18
Language	English
SDS	950632



SUMMARY

Pb-free - Halide-free - Premium latest technology No-Clean, Fine Pitch solder paste

PASTE	JEAN-151-SN100C-T4
PROCESS	
No-Clean process	9
Post-solder cleaning	9

INDUSTRY APPLICATION	
Standard electronics	8
Industrial electronics	9
Hi-Rel electronics (automotive)	9

PROCESS CAPABILITY	
Squeegee	9
ProFlow	TBD
Pb-free Profile Air, short	9
Pb-free Profile Air, long	8
Pb-free process N2	9
Vapor phase process	7
Shiny joint appearance	9
Cosmetic cleanliness	8
ICCT compatible	N/A
Conformal coating	N/A

Legend	
<i>Especially made for this purpose</i>	9 - 10
<i>Generally qualified for this purpose</i>	7 - 8
<i>Generally usable, but not the best choice</i>	5 - 6
<i>Generally not usable for this purpose</i>	3 - 4
<i>Wrong choice</i>	1 - 2

Check material compatibility with every process change!

Industrial chemical product.

Read MSDS before use.

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CLASSIFICATION	
DIN-EN-ISO-9454-1: 2016	1122
IPC-J-STD-004-A: 2004	ROLO
IPC-J-STD-005: 1995 (Powder)	T4
Particle size	[µm] 20-38

PROPERTIES		
Flux code	JEAN-151	
Alloy Code	SN100C	
Alloy composition	Sn99.3Cu0.7NiGe	
Liquidus	[°C]	227
Solidus	[°C]	227
Recommended peak temp.	[°C]	238-260
Acid number	[mg KOH/g]	123
Flux	[% w/w]	11.3
Residues	Colorless	
Tackiness Malcom TK1	IPC-TM-650 2.4.44	[gf] @ 0h 35

TEST REPORTS			
IPC/ANSI-J-STD-005			Compliant
Certificate of Compliance			Website
RoHS Compliant			Available
Application Note			EN/DE
Copper Mirror	IPC-TM-650 2.3.32		Pass
Halides	IPC-TM-650 2.3.33	[Silver Chromate]	Pass
Halide	IPC-TM-650 2.3.35.1	[Fluoride by Spot]	Pass
Copper Corrosion	IPC-TM-650 2.6.15		Pass
SIR	IPC-TM-650 2.6.3.3		Pass
ECM	IPC-TM-650 2.6.14.1		Pass

PACKAGING AND STORAGE		
Packaging jar	PP [g]	500
Packaging cartridge	HDPE [g]	650
Packaging cartridge	HDPE [g]	1300
Packaging Cassette Pro-Flow	[g]	800
Minimum shelf-life in months	4-10 °C	12